

# **Team #42: PCB Laser Etcher** Kevin Broadbridge, Will Fisher, Gregory Suhor, Jared Swetnam

Power 🚄

Controls

Systems

Ventilation

Supply

# Objective

Develop a machine that tangibly improves the creation of printed circuit boards and photomasks for the LSU PCB lab through increased precision and efficiency relative to existing processes.

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Specification	Target	Achieved
PCB Active Area	12" x 9"	13" x 11.8
PCB Production Time	< 1 hour	0.5 hours*
Machine Dimensions	< 2.5' x 6'	1.92' x 2.48
Trace Width Capability	< 8 mils	3 mils

\*Production time depends heavily on board size and the number of features.

# **Concept Selection**





Direct Exposure

Photomask Development

Safety





College of Engineering School of Electrical Engineering & Computer Science



# Prototype Design



#### Stop Laser T-Slot Frame Actuators

# Manufacturing Process

Table & Band Saws Acrylic panels **Soldering Iron, Heat Gun** Wire connections **Drill Press** 

Screw holes

**Laser Cutting Machine** Smaller acrylic panels **PCB** Milling Machine Printed circuit board **Fusion 360 Software** Smaller acrylic panels

## Engineering Analysis

Spot size due to diffraction =  $\frac{4M^2\lambda f}{\pi D}$ 

Diffusing Acrylic

 $\lambda = wavelength$ = lens focal lengthD = input beam diameter at the lens  $M^2 = beam mode parameter$ 

### November

### December

• Order Parts Initial Subsystem Manufacturing

Conclusion: Wavelength is proportional to trace width. Thus, the 405nm laser option is more precise than the 445nm option at a spot size of 4 mils versus  $\geq$  8 mils.

### January

- Subsystem
- Manufacturing
- Order Additional Parts

